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Patent claims

1. An arrangement (1)
comprising a component (2) for high-temperature
5 applications and at least one monitoring device (3) for
recording at least one crack (5) in the component (2),
in which the monitoring device (3) has at least one
electrically conductive monitoring structure (4) which
is decoupled from a function of the component (2) and
10 has a defined electrical property, and
in which the monitoring device (3) and the monitoring
structure (4) are not permanently electrically
connected to one another,
15 characterized

in that the monitoring structure (4) and the monitoring
device (3) form an electrical resonant circuit,
in that the component (2) and the monitoring structure
20 (4) are fixedly connected to one another in such a
manner,
in that the cracks (5) in the component (2) cause
cracks (17) in the monitoring structure (4) and
therefore a change in the defined electrical property
25 of the monitoring structure (4), and
in that the monitoring device (3) functions not only as
an emitter but also as a receiver,
so that it is possible to record a deviation in the
property of the resonant circuit (7) formed from
30 monitoring structure (4) and monitoring device (3) as a
result of the change.

2. The arrangement as claimed in claim 1, in which
the degradation (5) of the component and/or the
35 degradation (17) of the monitoring structure is
selected from the group consisting of deformation

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and/or removal of material and/or crack formation
and/or crack propagation.

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3. The arrangement as claimed in claim 1 or 2, in which the monitoring structure (4) has at least one electrical resonant circuit (7).

5 4. The arrangement as claimed in one of claims 1 to 3, in which the monitoring structure (4) includes at least one electrically conductive conductor material selected from the group consisting of metallic conductors and/or ceramic conductors.

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5. The arrangement as claimed in claim 4, in which a component material of the component and the conductor material of the monitoring structure have a substantially identical mechanical property.

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6. The arrangement as claimed in claim 5, in which the mechanical property is selected at least from the group consisting of thermal expansion behavior and/or fracture toughness.

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7. The arrangement as claimed in one of claims 1 to 6, in which the monitoring structure (4) is arranged at a surface portion (10) of the component (2) and/or in the volume of the component (2).

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8. The arrangement as claimed in one of claims 1 to 7, in which the component (2) is a heat shield of a combustion chamber.

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9. The arrangement as claimed in claim 8, in which the monitoring structure (4) is arranged at a surface portion (10) of the heat shield (2) which is remote from an interior space (6) of the combustion chamber.

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10. A process for producing the arrangement as claimed in one of claims 1 to 8, comprising the process steps of:

- a) arranging the component (2) and the monitoring structure (4) against one another, and
- b) fixedly connecting the component and the monitoring structure (4),
- c) providing a monitoring device (3) which is not permanently electrically connected to the monitoring device (4).

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11. The process as claimed in claim 10, in which a ceramic is used as component material of the component and/or as conductor material of the monitoring structure, and joint sintering of the component and the monitoring structure is carried out to fixedly connect the component and the monitoring structure.

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12. A method for checking the ability of a component (1) to function using the arrangement as claimed in one of claims 1 to 9, comprising the method steps of:

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- a) determining an actual value of at least one defined electrical property of the monitoring structure (4) by means of the monitoring device (3), with an electrical or electromagnetic coupling being produced between monitoring structure (4) and monitoring device (3),
- b) comparing the actual value of the electrical property

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with a desired value, representing the ability of the component (1) to function, of the electrical property.

13. The method as claimed in claim 12, in which the
5 defined electrical property of the monitoring structure is selected from the group consisting of DC resistance and/or impedance and/or radiofrequency resonance property.

10 14. The method as claimed in claim 12 or 13, in which the determination of the actual value of the defined electrical property is carried out in an operating phase of the component and/or in a stationary phase of the component.